

Title (en)
Method for the treatment of metal materials

Title (de)
Verfahren zur Behandlung metallischer Werkstoffe

Title (fr)
Méthode de traitement de matériaux métalliques

Publication
EP 1214995 A2 20020619 (DE)

Application
EP 01127929 A 20011123

Priority
DE 10062310 A 20001214

Abstract (en)
Process for treating metallic materials, especially for consolidating the structure of metallic materials comprises producing a blank of the metallic materials, heating to a deformation temperature and deforming the blank. An Independent claim is also included for a blank made from titanium aluminide. Preferably deformation is exerted by producing torsion or compressing. Heating is carried out using electrical induction. Deformation is carried out at 1,000 degrees C.

Abstract (de)
Es wird ein Verfahren zur Behandlung metallischer Werkstoffe, insbesondere zur Konsolidierung des Gefüges metallischer Werkstoffe, vorgeschlagen. Das Verfahren umfaßt folgende Verfahrensschritte: a) Erzeugung eines Rohlings aus metallischem Werkstoff, b) Erwärmung des Rohlings auf Umformtemperatur sowie, c) Deformierung des Rohlings. <IMAGE>

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Cited by
CN110014155A; KR100505168B1; US10907228B2; US10907227B2; US10907226B2; EP3670680A1; EP3670681A1; EP3670679A1

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